

# Part Number: XZUR56WT-5

3.0x1.0 mm SMD CHIP LED LAMP

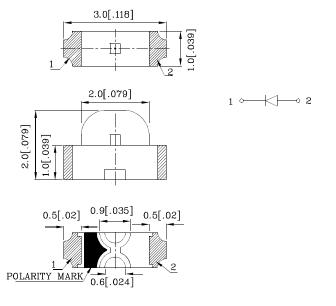
## **Features**

- Ideal for indication light on hand held products
- $\bullet$  Long life and robust package
- Variety of lens types and color choices available
- Tinned pads for improved solderability
- Package: 2000pcs / reel
- $\bullet$  Moisture sensitivity level : level 3
- RoHS compliant





# Package Schematics



### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.15(0.006")$  unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		UR (GaAsP/ GaP)	Unit	
Reverse Voltage	$V_{\mathrm{R}}$	5	V	
Forward Current	$I_{\mathrm{F}}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\mathrm{FS}}$	160	mA	
Power Dissipation	$P_{D}$	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		

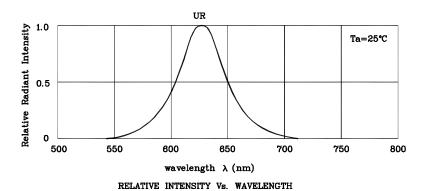
Operating Characteristics (T <sub>A</sub> =25°C)		UR (GaAsP/GaP)	Unit	
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2	V	
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2.5	V	
Reverse Current (Max.) (V <sub>R</sub> =5V)	$I_R$	10	uA	
Wavelength of Peak Emission (Typ.) (I <sub>F</sub> =20mA)	λΡ	627	nm	
Wavelength of Dominant Emission (Typ.) (I <sub>F</sub> =20mA)	λD	625	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$\triangle \lambda$	45	nm	
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	15	pF	

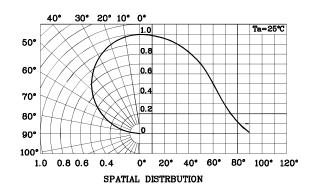
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous\\ Intensity\\ (I_F=20mA)\\ mcd \end{array}$		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZUR56WT-5	Red	GaAsP/GaP	Water Clear	8	14	627	120°

Apr 12,2011 XDSB4955 V3 Layout: Maggie L.

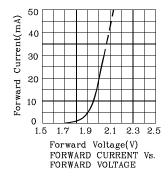


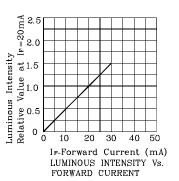


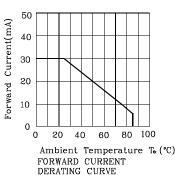


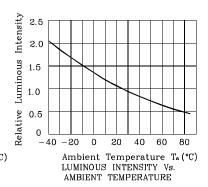


# **UR**



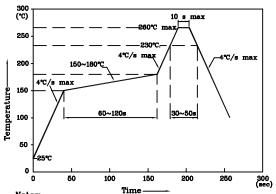






# LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

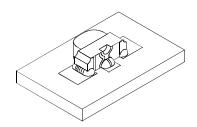


- notes:
  1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

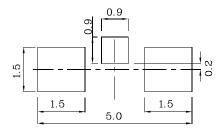




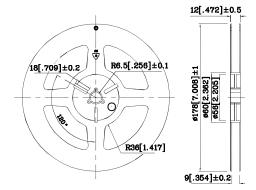
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



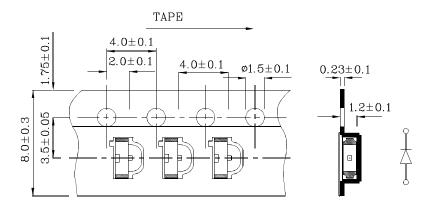
**♦** Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



# **❖** Reel Dimension



# **❖** Tape Specification (Units:mm)



### Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

Apr 12,2011

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# PACKING & LABEL SPECIFICATIONS

